

*Mesures autour des couplages oxydation haute température-mécanique*



Compiègne, 5-6 juin 2019

# Relations entre microstructure induite par l'oxydation et adhérence : cas de l'acier Fe-17,5Cr-8,1Ni (304 L)

Valérie PARRY, Muriel BRACCINI, Céline PASCAL,  
Guillaume PARRY



Grenoble INP



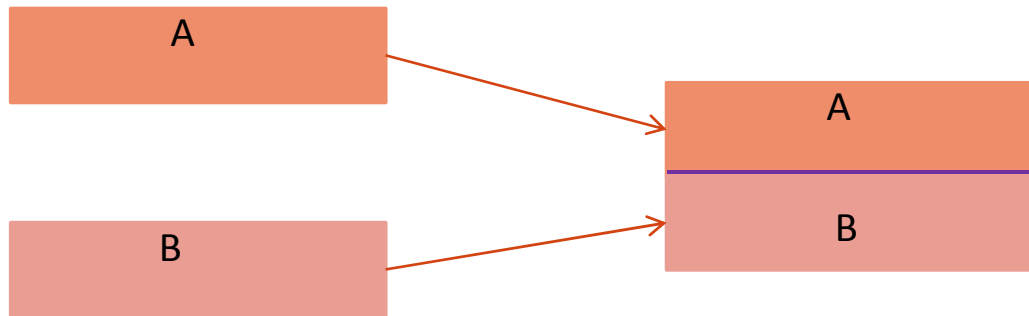
Communauté  
UNIVERSITÉ Grenoble Alpes

# Mesure d'adhérence ?

---

$G_c$  toughness or fracture energy ( $\text{J.m}^{-2}$ )

$$G_c = W_{adhesion} + W_{dissipative}$$

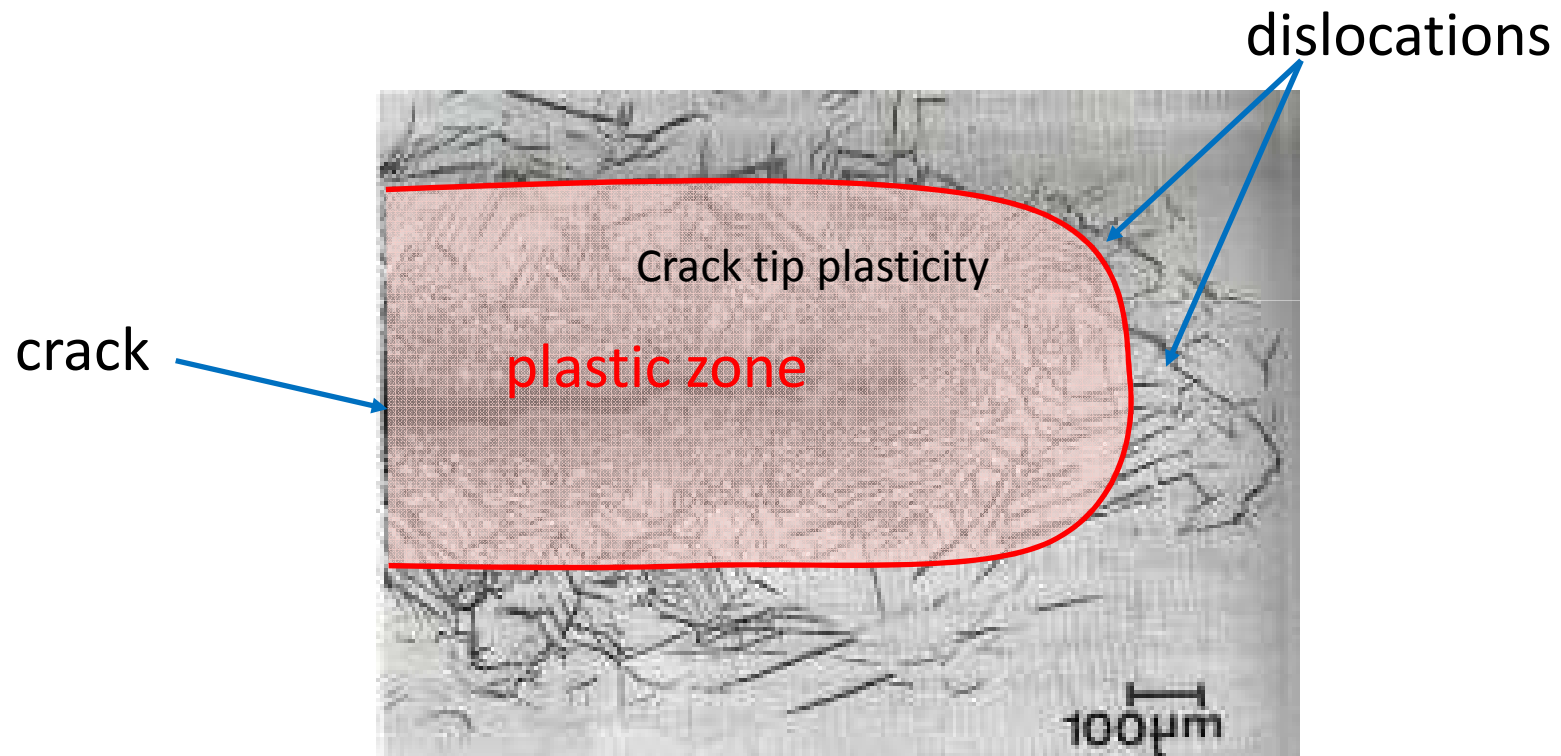


$$W_{adhesion} = \gamma_A + \gamma_B - \gamma_{AB} \cong 1 \text{ J.m}^{-2}$$

# Mesure d'adhérence ?

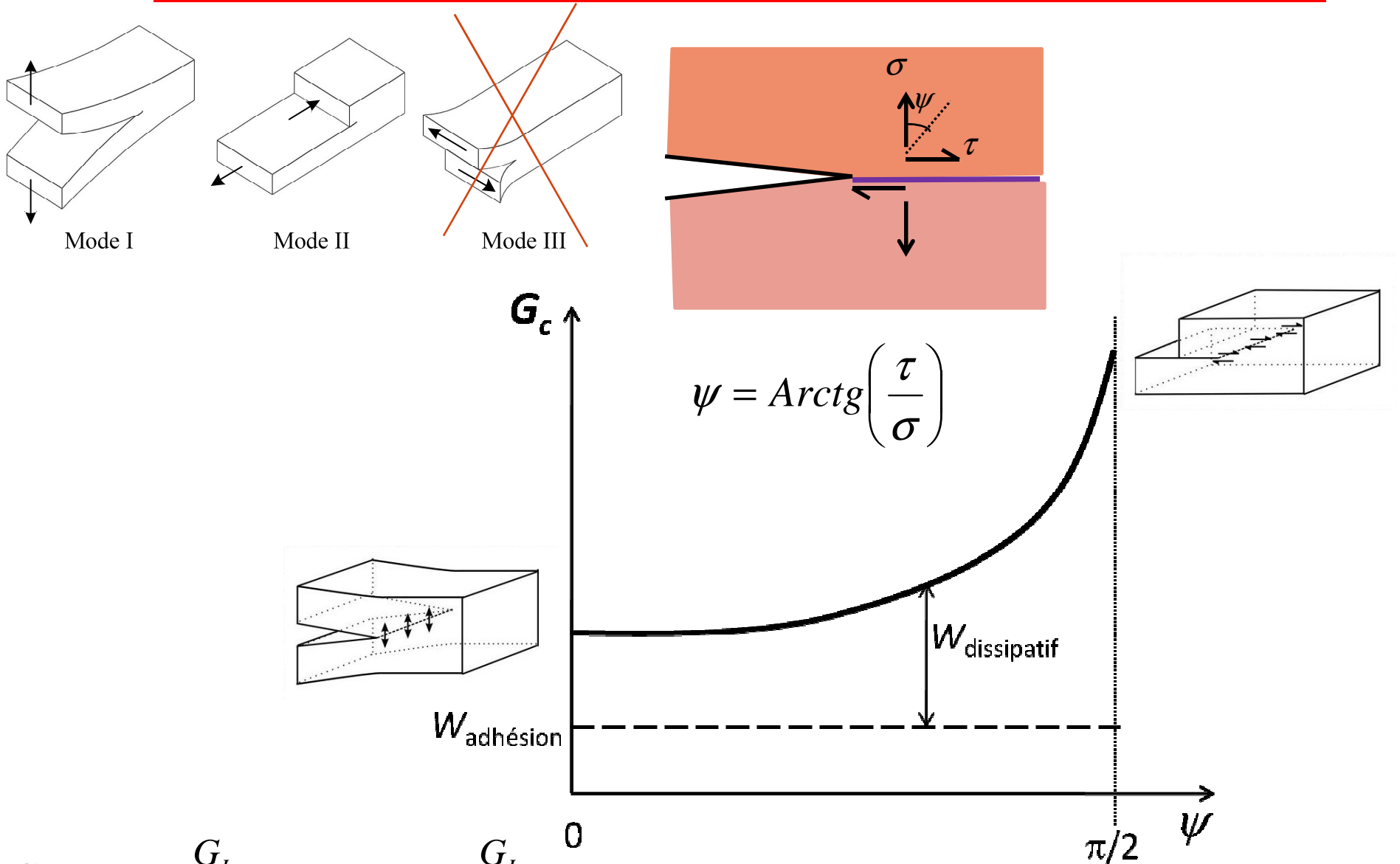
$G_c$  toughness or fracture energy ( $J.m^{-2}$ )

$$G_c = W_{adhesion} + W_{dissipative}$$



$$W_{adhesion} \ll W_{dissipative}$$

# Propagation d'une fissure interfaciale



$$G_c = \frac{G_{Ic}}{\cos^2 \psi + \lambda \sin^2 \psi} = \frac{G_{Ic}}{1 + (\lambda - 1) \sin^2 \psi} \quad 0 \leq \lambda \leq 1$$

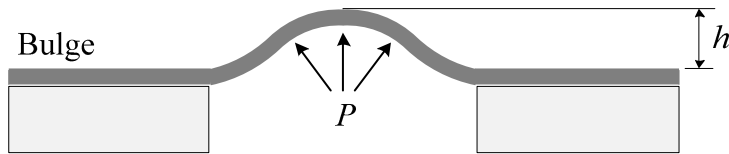
# Adhesion measurement methods

Before testing

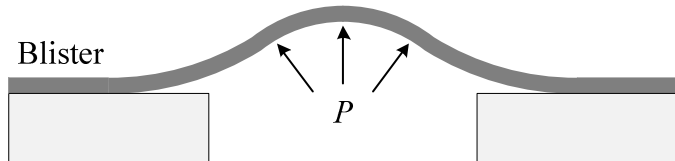


Stainless steel foil	
	Oxide
	Glue
	Sample holder

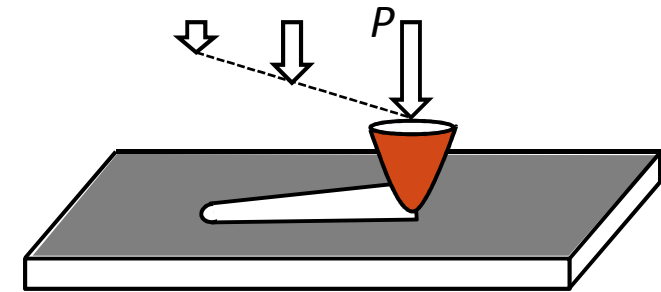
Bulge



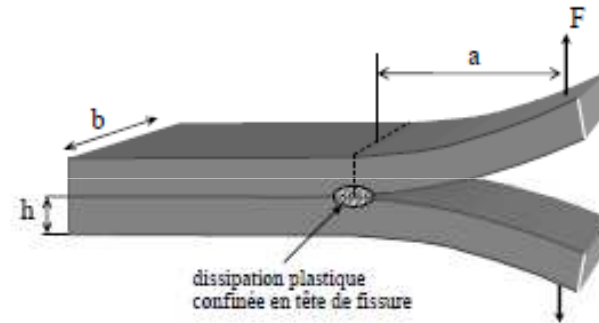
Blister



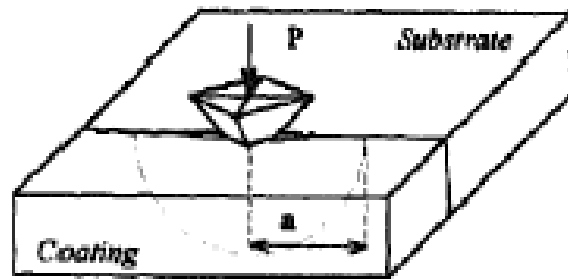
*Inverted blister test*



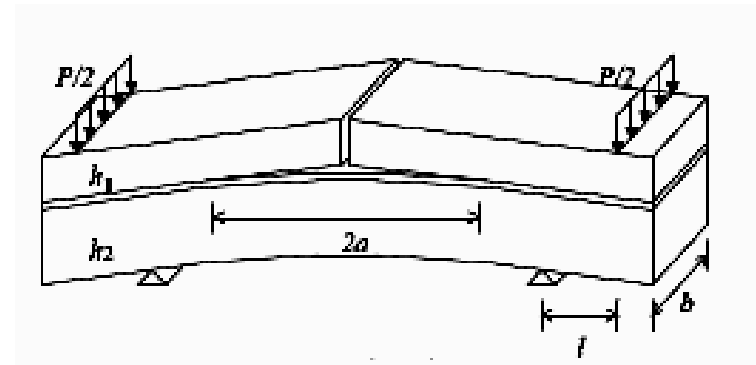
*Scratch test*



*Wedging*



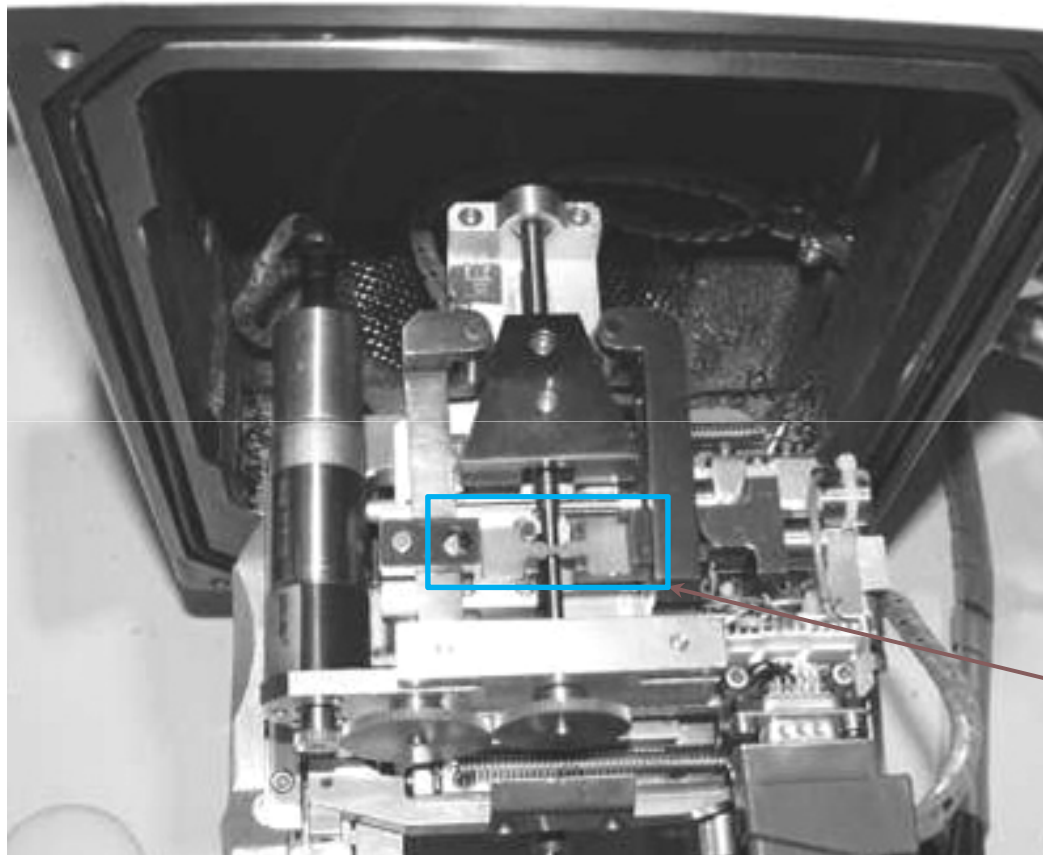
*Interfacial indentation test*



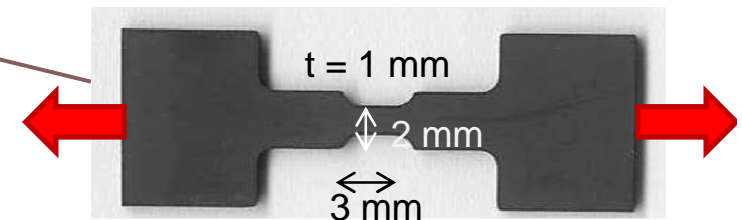
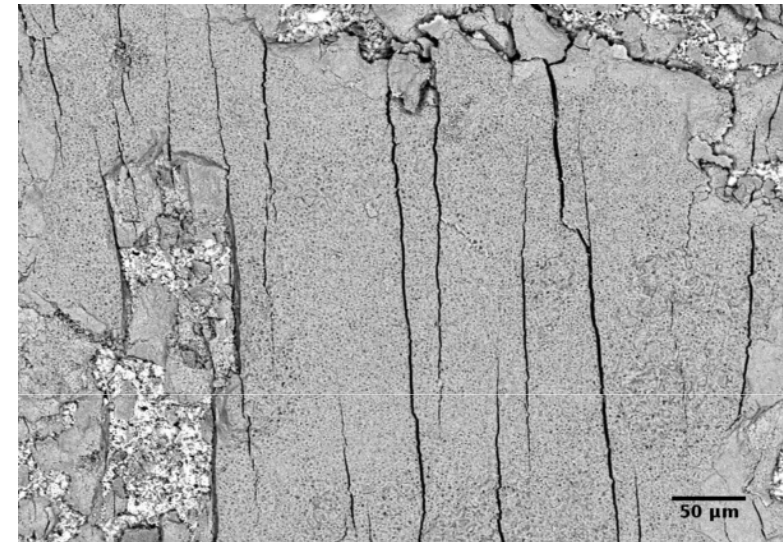
*3- or 4-point bending*

# Adhesion measurement methods

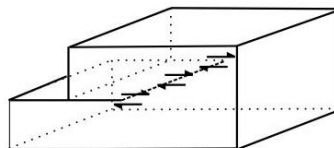
- SEM *in-situ* tensile testing



AISI 303 - 50 h – 1000 °C - air

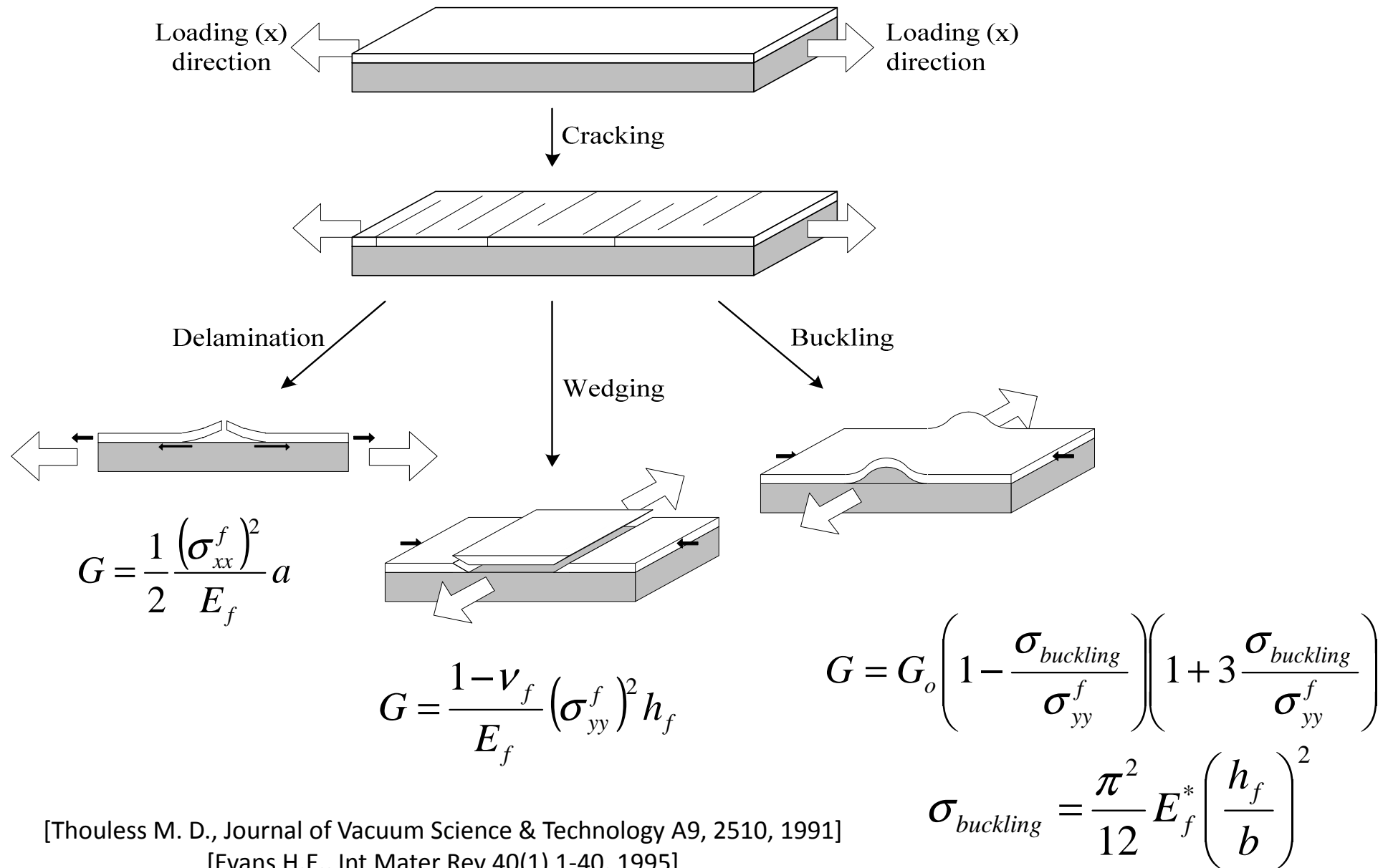


Mode mixity  $\Psi \Rightarrow \pi/2$



displacement rate =  $50 \mu\text{m} \cdot \text{min}^{-1}$

# Tensile testing



[Thouless M. D., Journal of Vacuum Science & Technology A9, 2510, 1991]

[Evans H.E., Int Mater Rev 40(1) 1-40, 1995]

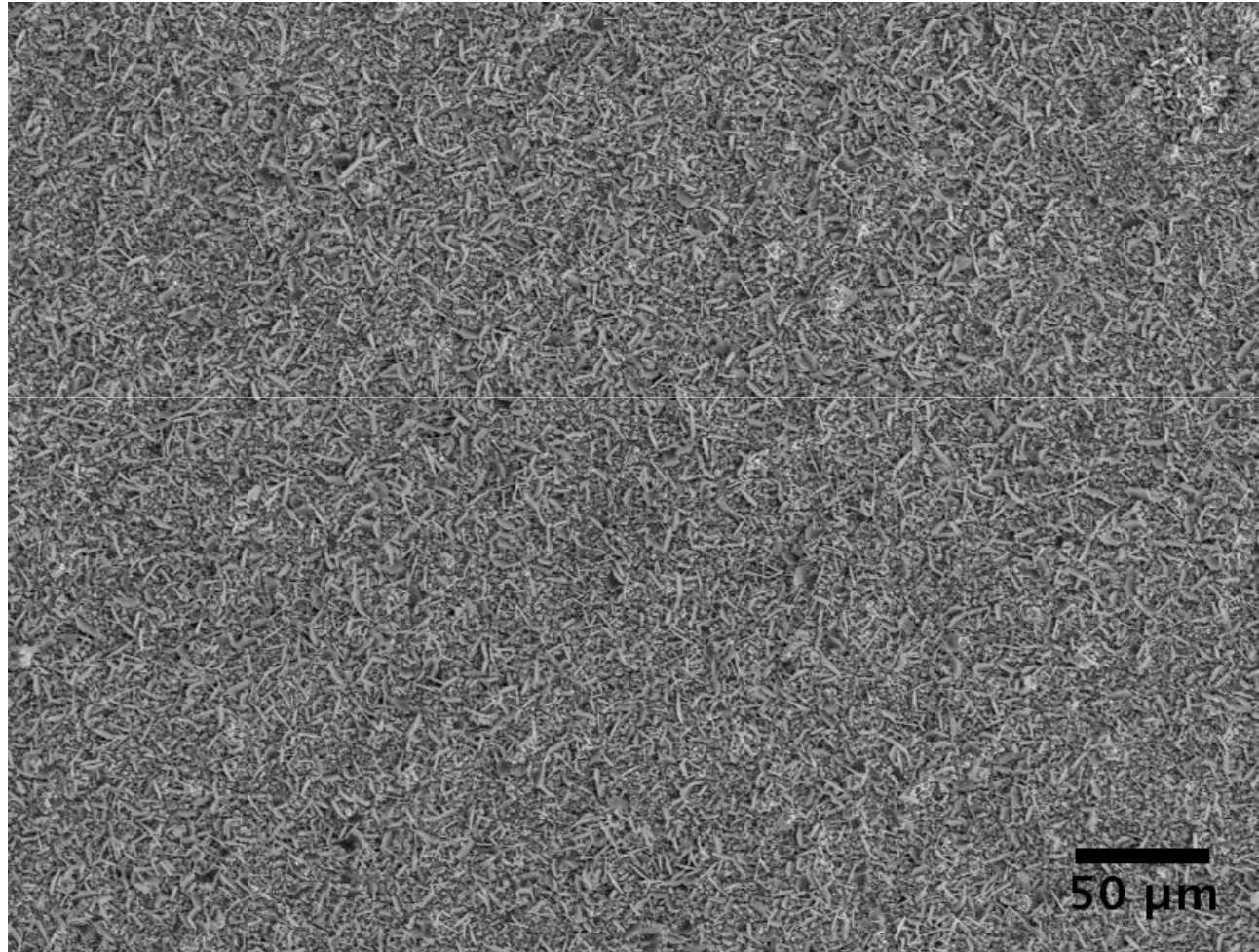
[Hutchinson J.W., Suo Z., Adv. Appl. Mater. 29 63-191, 1992]



# Understanding tensile testing pattern

---

AISI 304L previously oxidised at 900 °C for 50h air  
SEM (SE mode) *in-situ* tensile testing experiment 0->63% strain



E. Fedorova et al. Corrosion Science. 103, 145 (2016)

V. Parry et al. Oxid Met 88, 29–40 (2017)

C. Pascal et al. Material Characterization 127, 161–170 (2017)

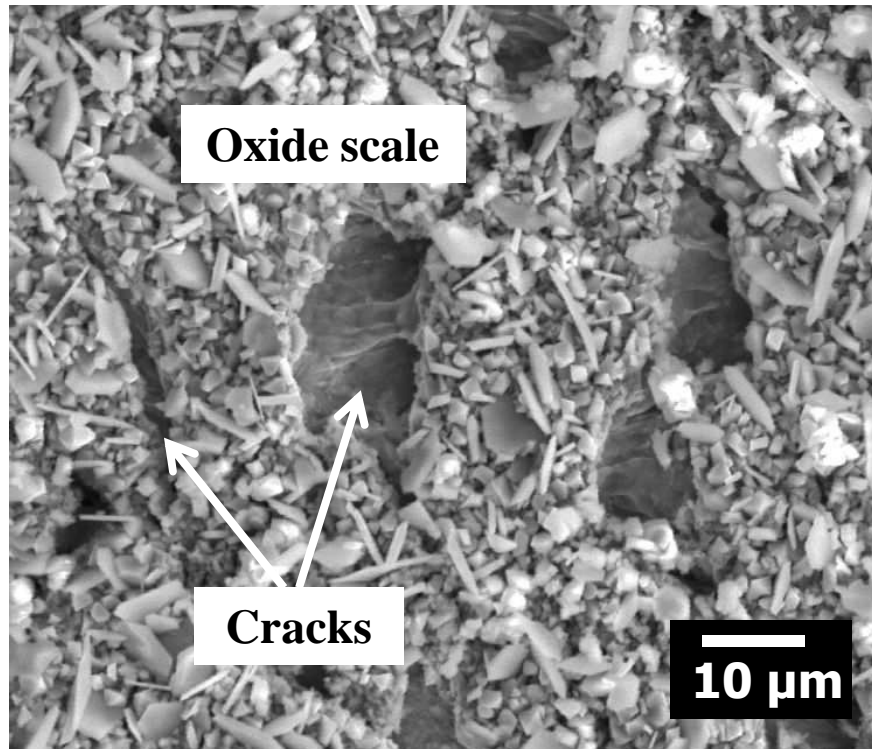


# Understanding tensile testing pattern

SEM Surface view (BES)

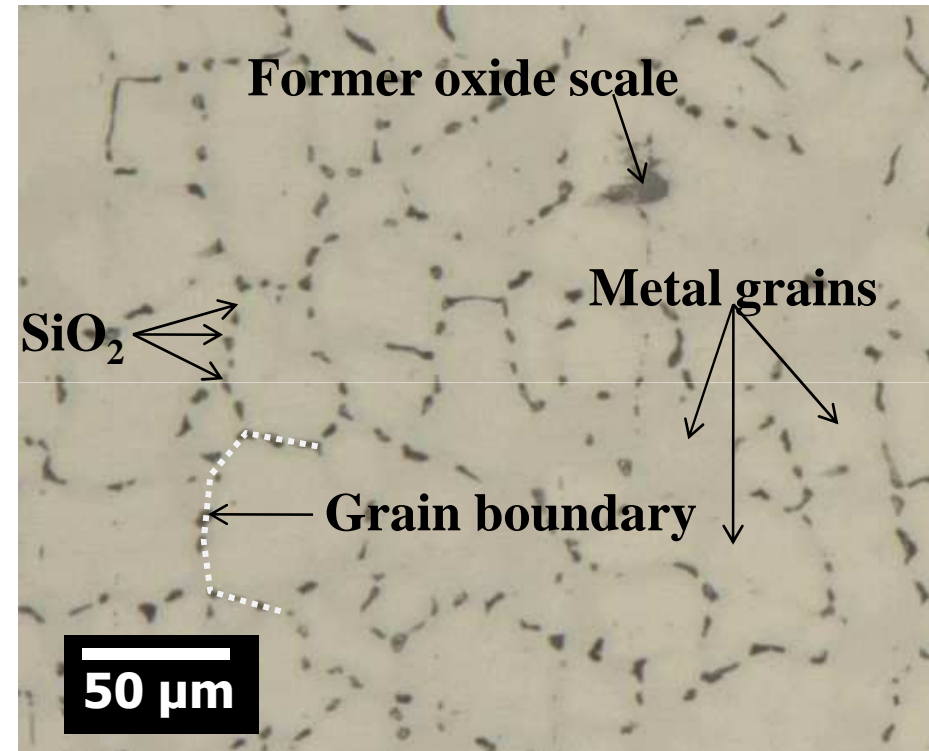
$\epsilon = 0.63$

← Tensile direction →



- Cracks opening in relation with the plastic deformation of the substrate
- Some cracks are not open

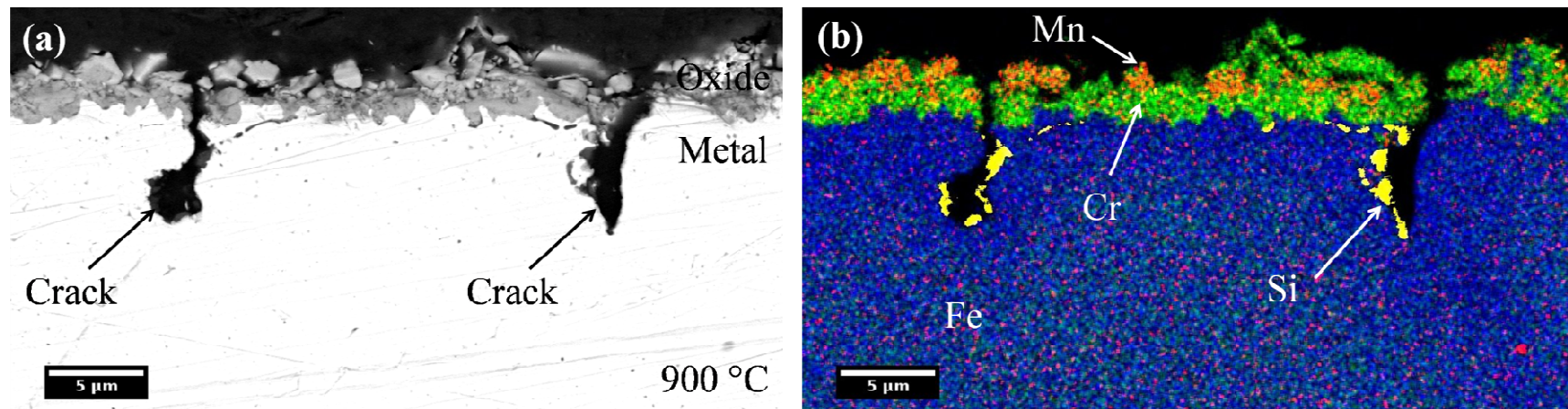
Optical microscope  
(after oxide scale polishing)



- strings of small SiO<sub>2</sub> precipitates decorate the substrate grains boundaries

# Understanding tensile testing pattern

- Internal oxidation of Si plays a key role on the overall mechanical behavior during tensile testing.
- The cracks are linked to the silica embrittlement of the substrate grain boundaries



**Can we predict this failure pattern ?**

**i.e. oxide scale spallation vs. inclusion debonding**

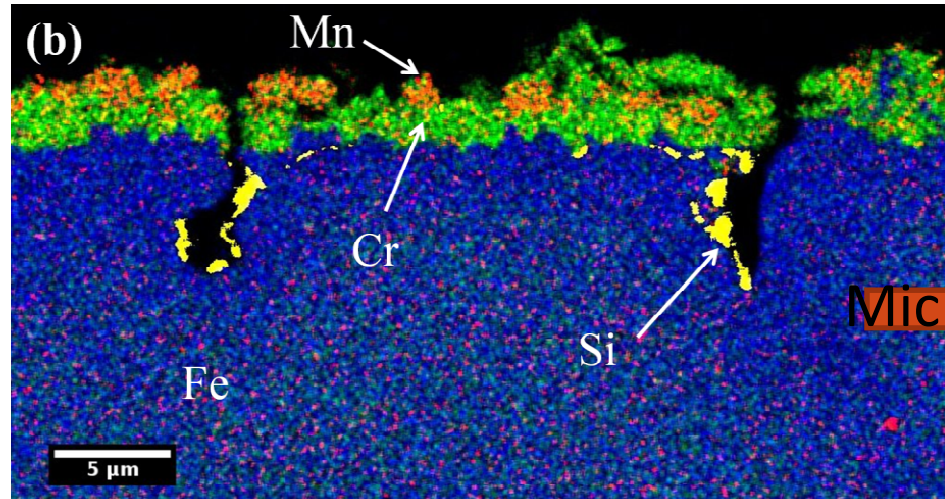
=> **Objectives** : investigation of the relevant parameters controlling the silica/alloy interface debonding.

=> **Tools** : micromechanical modeling using cohesive zone models

# Micromechanical modeling

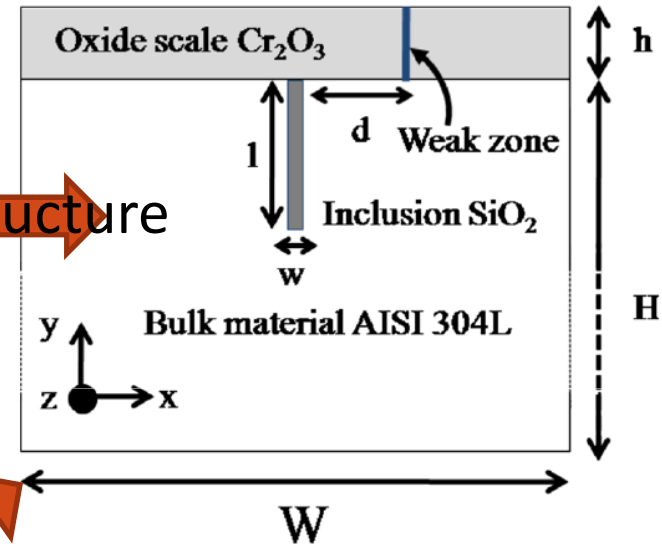
Experiments

Model



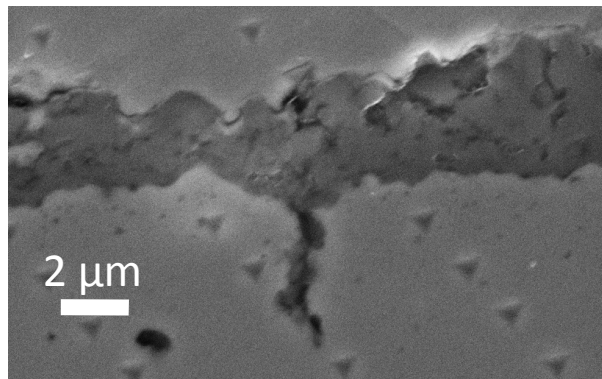
The cracks are linked to the silica embrittlement of the substrate grain boundaries

Collab G. Parry

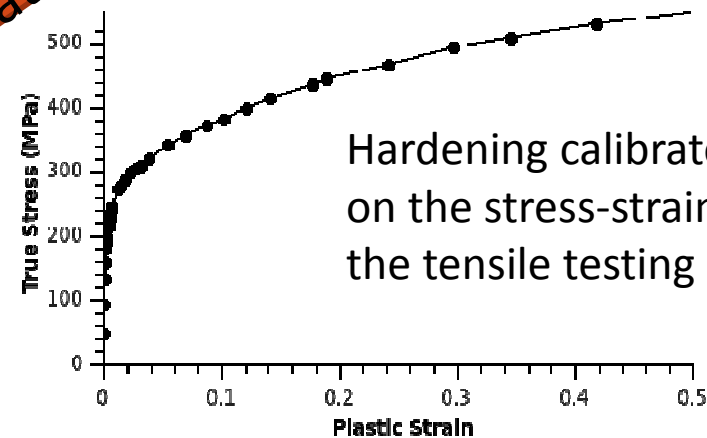


Microstructure

Materials



Young moduli measurements

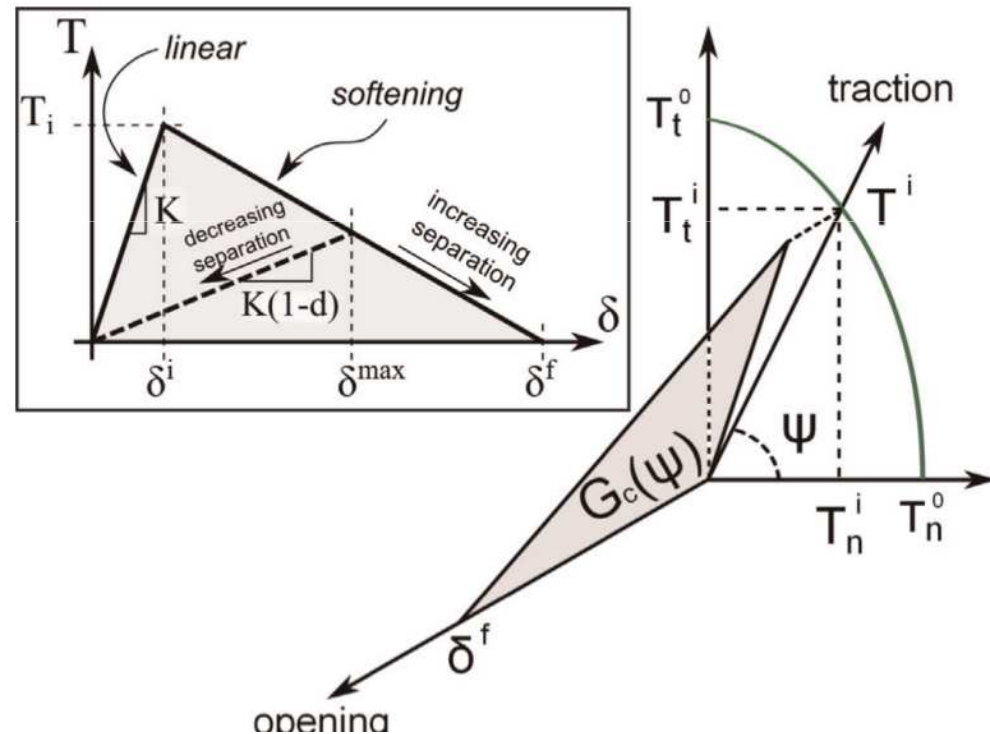
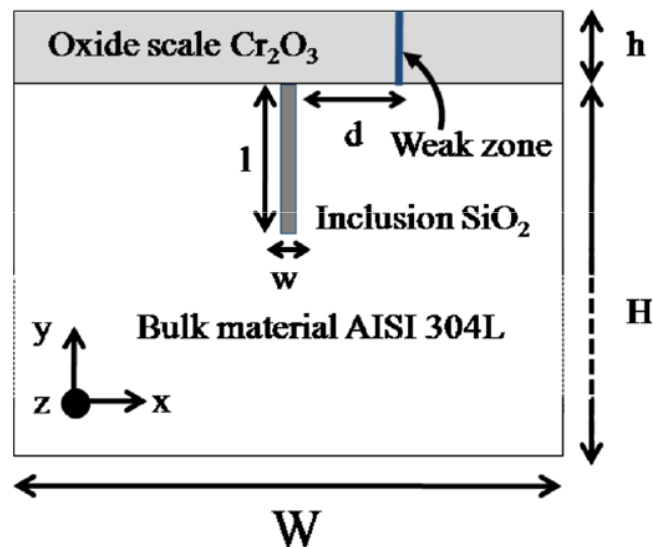


Hardening calibrated based on the stress-strain curve of the tensile testing



# Cohesive zone model

- Allow accounting for crack initiation and propagation
- Traction *versus* separation law describing interface fracture behavior
- Can include mixed mode dependence



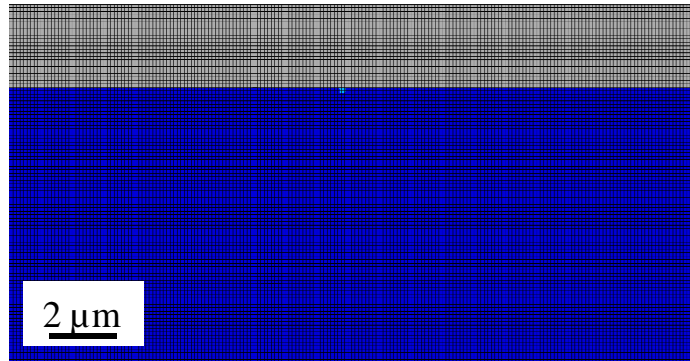
2 parameters:  $G_c$  and  $T_{max}$

Peak maximum traction

# Results – conditions for interfaces decohesion

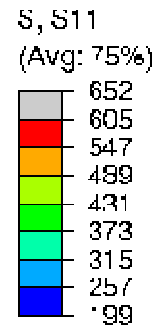
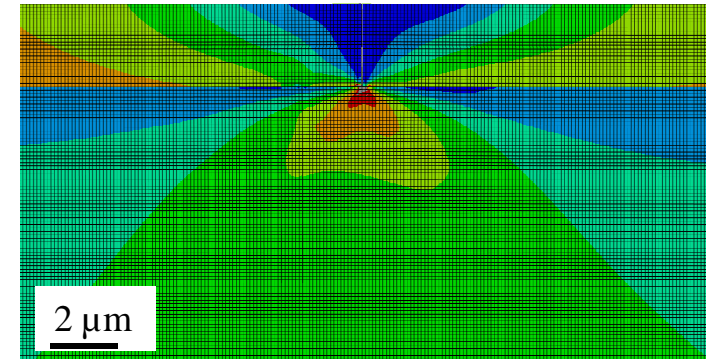
**Right before oxide scale cracking**

Normal stress S11 (MPa)



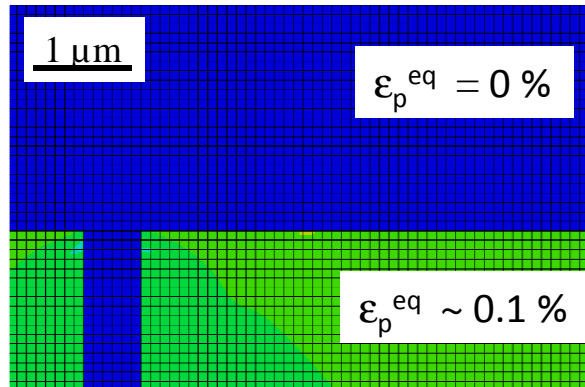
- High stress level in the oxide scale

**Right after oxide scale cracking**



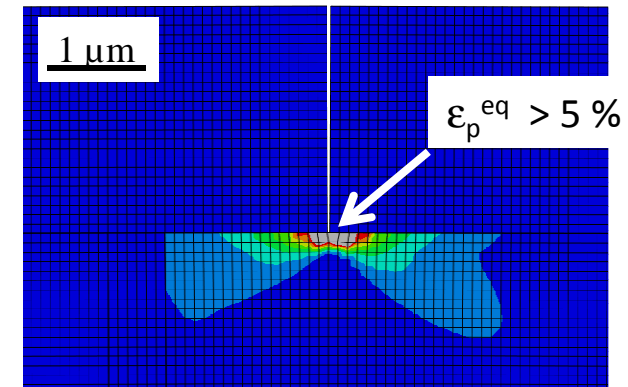
- Stress in the oxide scale is relaxed  
- Stress concentration in the metal beneath the crack tip.

**Applied strain  $\epsilon = 0.26\%$**



Equivalent plastic strain  $\epsilon_p^{eq}$

**Applied strain  $\epsilon = 0.28\%$**



- The plastic strain in the metal propagates with increasing loading from the stress concentration zone at crack tip into the bulk and can reach the inclusion

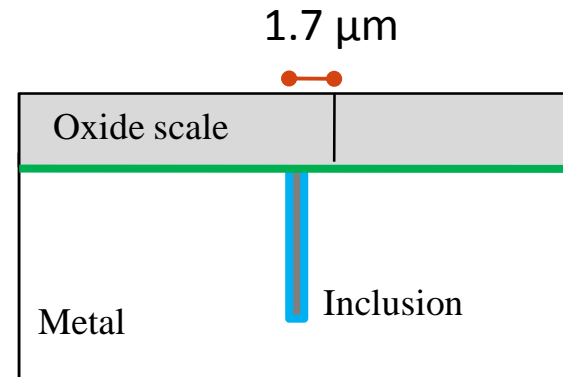


# Results – conditions for interfaces decohesion

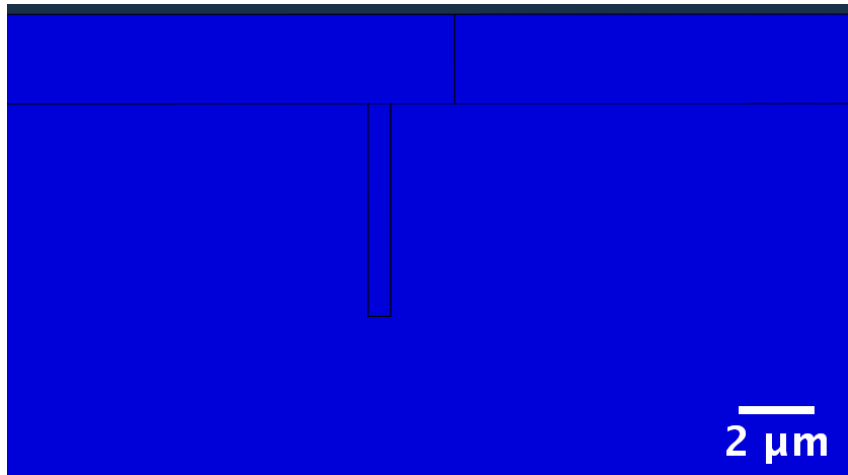
$$R = \frac{\sigma^{\max} \text{ metal inclusion interface}}{\sigma^{\max} \text{ metal oxide interface}}$$

With :

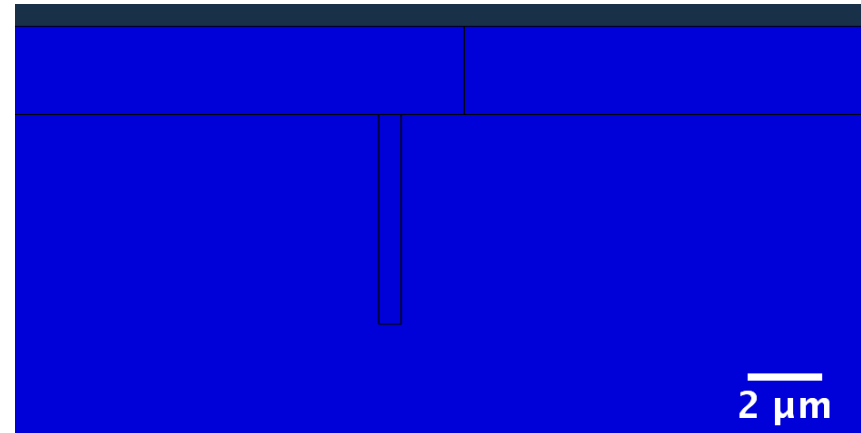
$\sigma_{n,MO}^{\max}$	600 MPa	$\sigma_{n,MI}^{\max}$	From 0.1 to 1.5 $\sigma_{n,MO}^{\max}$
$\sigma_{t,MO}^{\max}$	$5 \times \sigma_{n,MO}^{\max}$	$\sigma_{t,MI}^{\max}$	$5 \times \sigma_{n,MI}^{\max}$
$G_{c,MO}$	3 J.m <sup>-2</sup>	$G_{c,MI}$	From 0.5 to 1 $G_{c,MO}$



**R < 1** Inclusion debonding



**R > 1** Oxide scale debonding

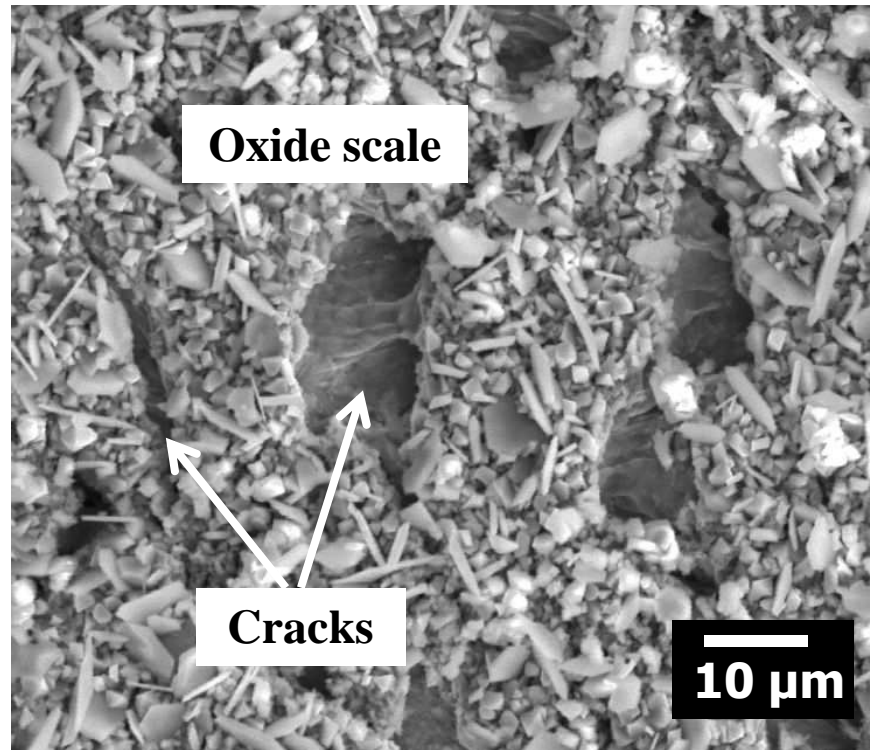


# What about the other cracks ?...

SEM Surface view (BES)

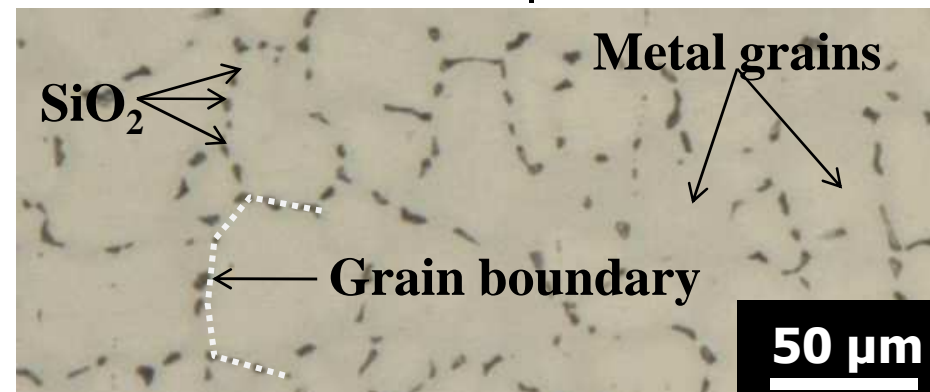
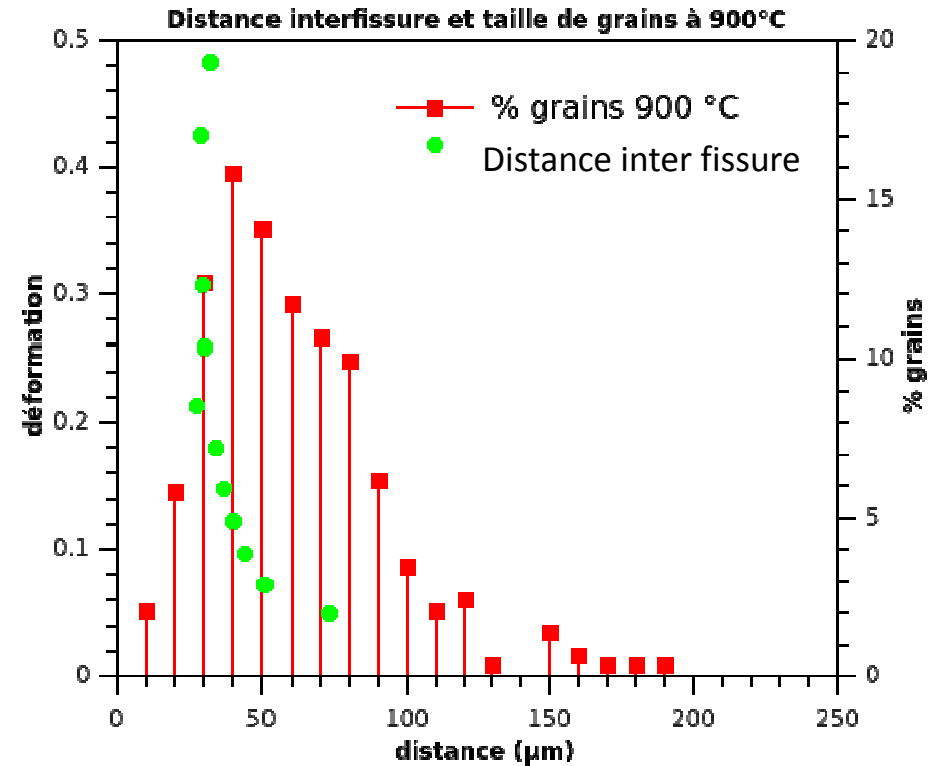
$\epsilon = 0.63$

← Tensile direction →



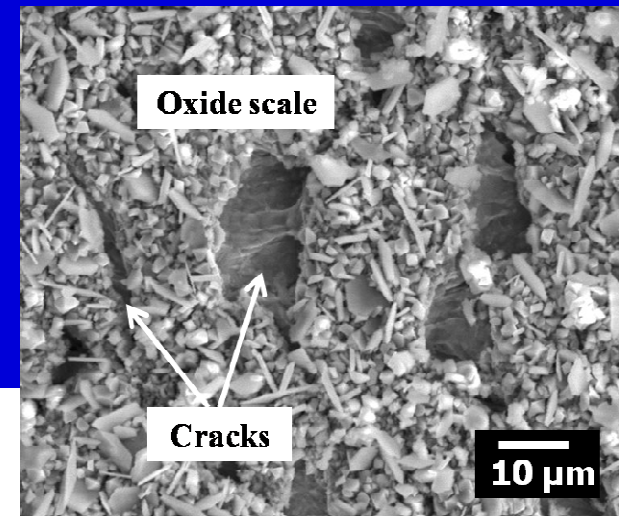
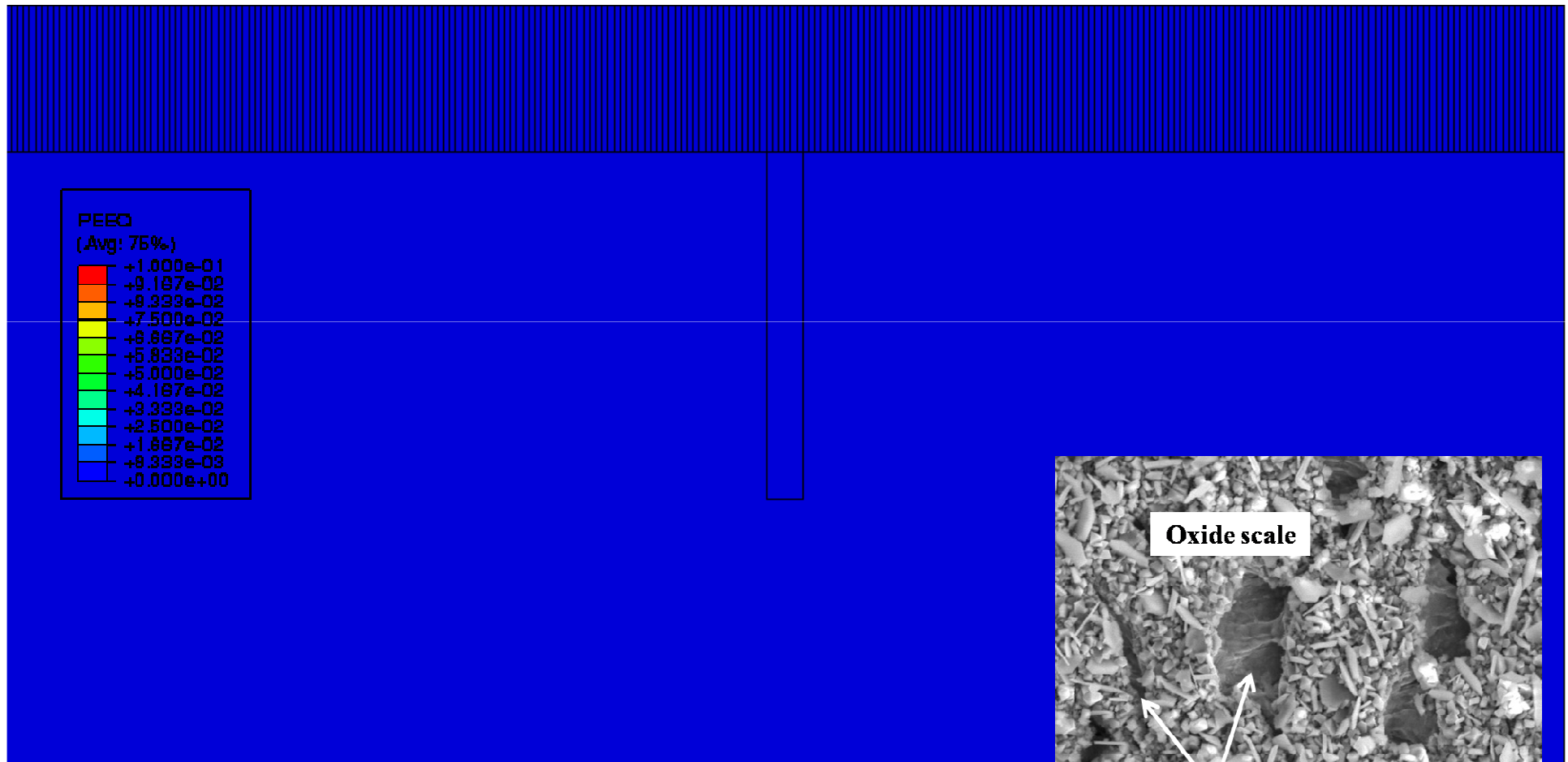
- Cracks opening in relation with the plastic deformation of the substrate
- Cracks not open

$d_{sat} = 29 \mu\text{m} < \text{grain size}$



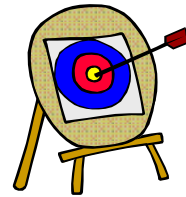
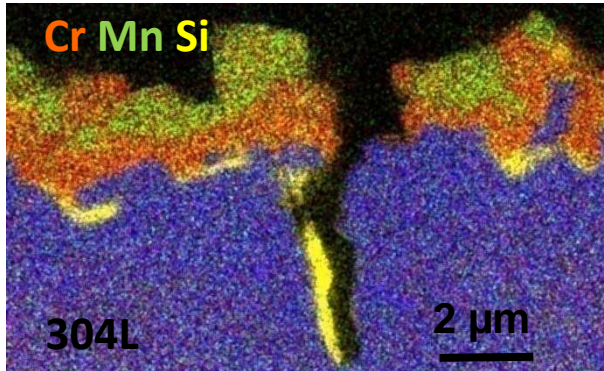
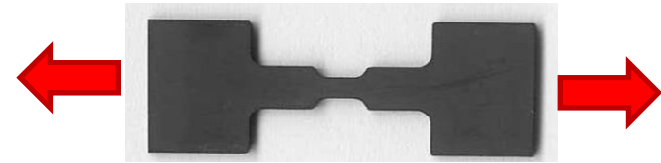
# What about the other cracks ?...

CZM in the oxide with a random distribution of maximum traction values





Mesure d'adhérence de la couche d'oxyde par essai de traction *in-situ* sous MEB



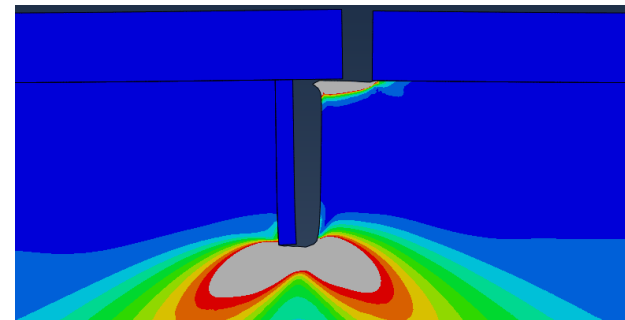
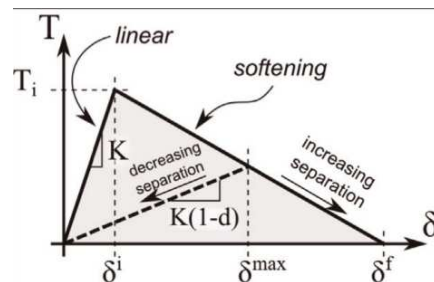
La formation de silice le long des joints de grains modifie le comportement mécanique de la zone affectée par l'oxydation

Lien entre mesure globale (adhérence) et effet local (microstructure) ??

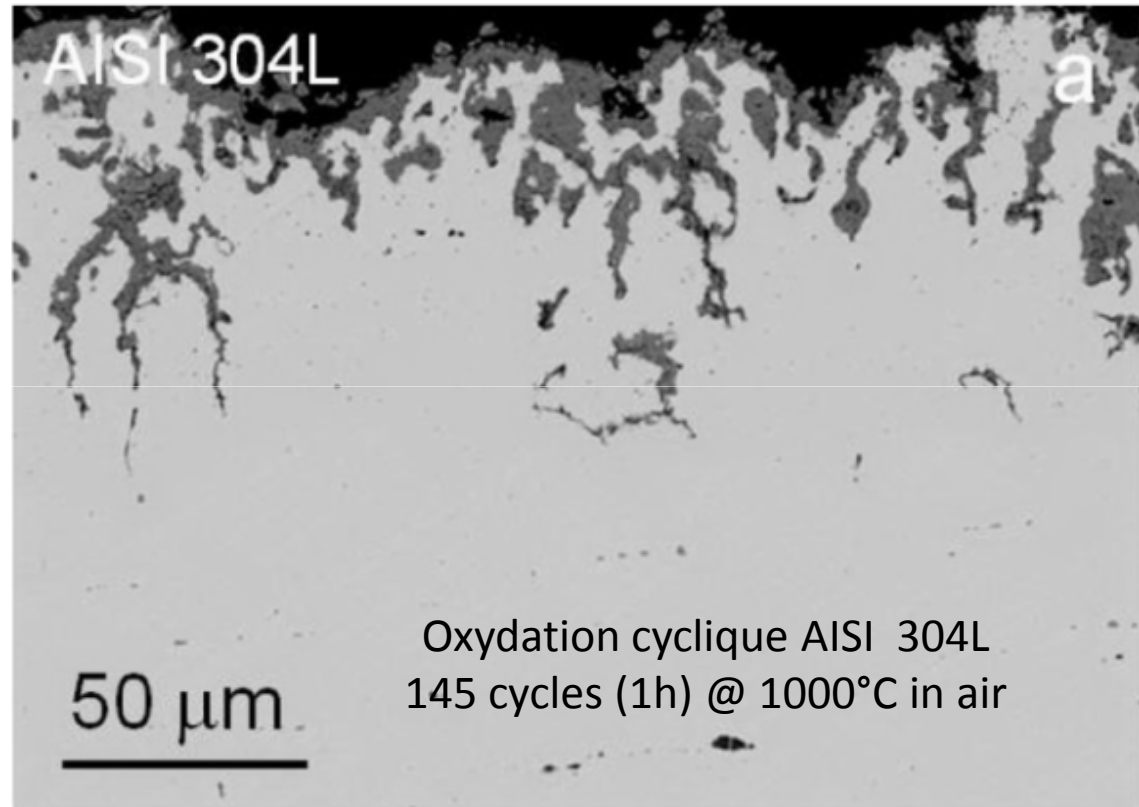
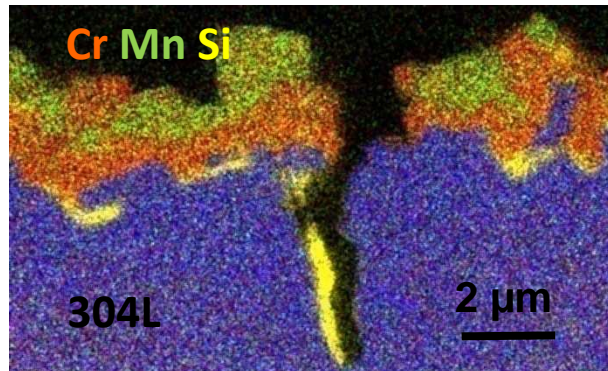
Quid si sollicitation mécanique différente (e.g. blister test) => Effet d'ancrage ?

Compétition entre décohésion métal/oxyde et métal/silice

=> modèle micromécanique utilisant des CZM pour décrire le pattern de fissuration.



Essai de traction *in-situ* sous MEB  
Oxydation isotherme AISI 304L @1000°C



*E. Fedorova et al. Corrosion Science. 103, 145 (2016)*

**Améliorer les modèles et simulations**  
en intégrant la géométrie (ondulation)  
Quantitatif  
Effet thermique